

### SOD-323 Plastic-Encapsulate Diodes

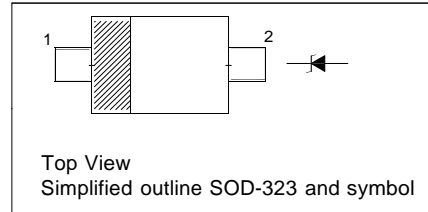
ZENER DIODE

#### FEATURES

- Planar Die Construction
- General purpose, Medium current
- Ideally suited for automated assembly processes
- Available in Lead free version

PINNING

PIN	DESCRIPTION
1	Cathode
2	Anode



**MARKING: H8**

#### MAXIMUM RATINGS(Operating temperature range applies unless otherwise specified)

Symbol	Parameter	Value	Unit
$P_D$	Power Dissipation(Note 1)	200	mW
$R_{\theta JA}$	Thermal Resistance from Junction to Ambient	625	°C/W
$T_j$	Operating Junction Temperature	150	°C
$T_{stg}$	Storage Temperature Range	-55~+150	°C

#### ELECTRICAL CHARACTERISTICS( $T_a=25^\circ\text{C}$ unless otherwise specified)

Parameter	Symbol	Test conditions	Min	Typ	Max	Unit
Zener Voltage Range (Note 2)	$V_Z$	$I_{ZT}=5\text{mA}$	5.1		5.5	V
Maximum Zener Impedance(Note 3)	$Z_{ZT}$	$I_{ZT}=5\text{mA}$			50	Ω
	$Z_{ZK}$	$I_{ZK}=1\text{mA}$			450	
Maximum Reverse Current (Note 2)	$I_R$	$V_R=2\text{V}$			2	μA
		$V_R=4.2\text{V}$			50	μA
Forward Voltage (Note 2)	$V_F$	$I_F = 10\text{mA}$			0.9	V

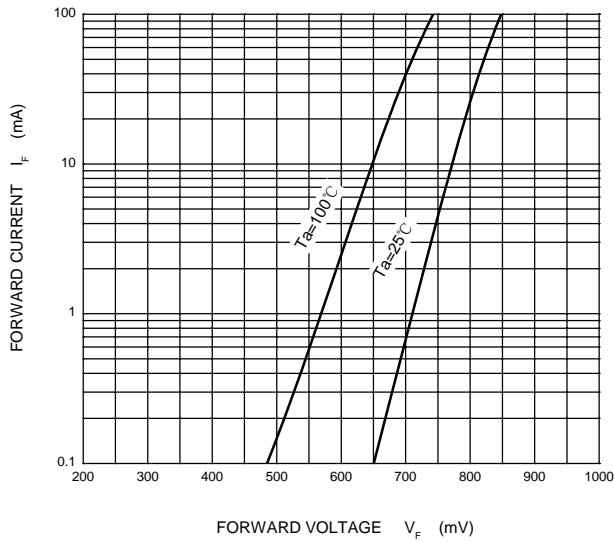
Notes: 1. Device mounted on ceramic PCB: 7.6mm x 9.4mm x 0.87mm with pad areas 25mm<sup>2</sup>.

2.Short duration test pulse used to minimize self-heating effect.

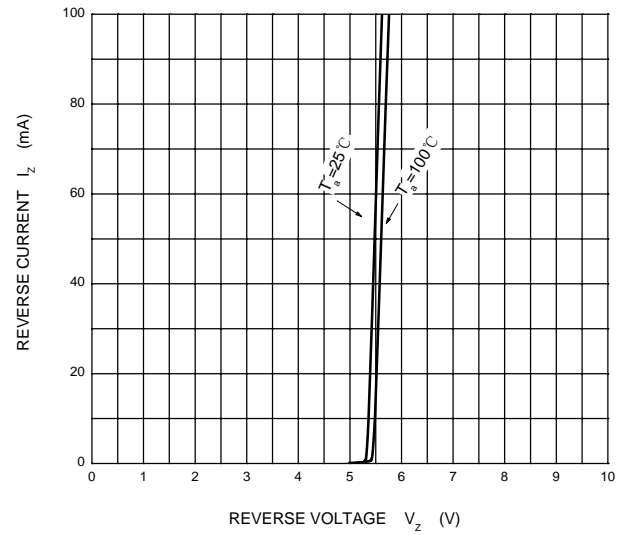
3. f=1kHz

## ELECTRICAL CHARACTERISTICS

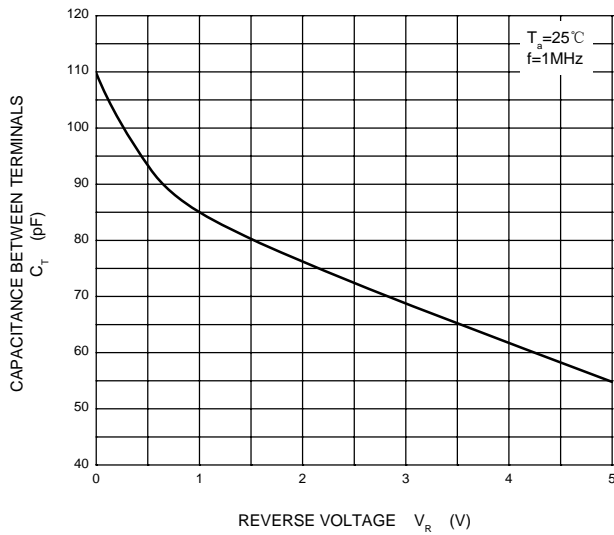
**Forward Characteristics**



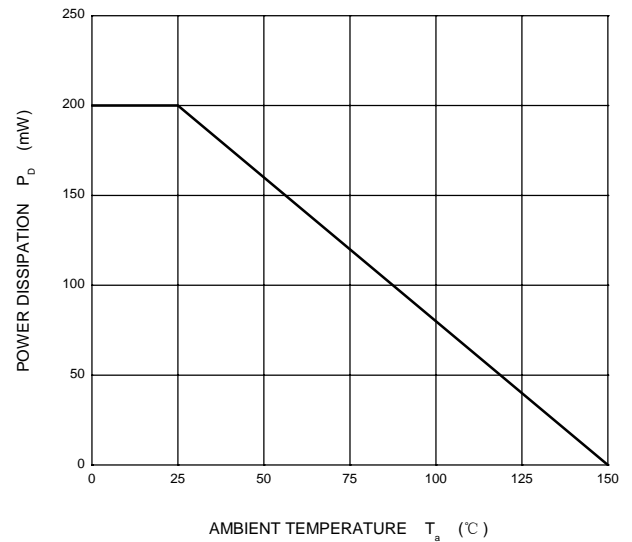
**Reverse Characteristics**



**Capacitance Characteristics**



**Power Derating Curve**

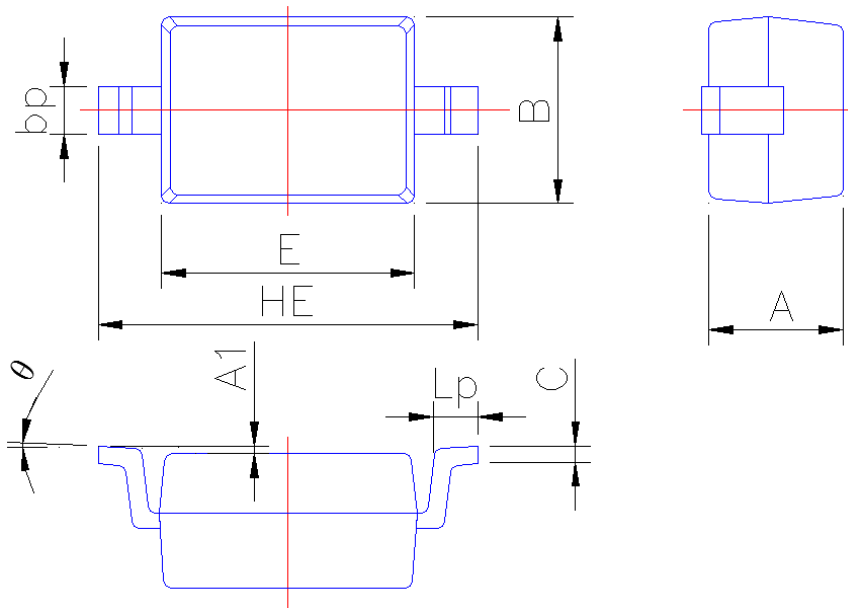




## PACKAGE OUTLINE

Plastic surface mounted package; 2 leads

SOD-323



Symbol	Dimension in Millimeters	
	Min	Max
A	0.95	1.15
A1	0.010	0.100
B	1.20	1.40
bp	0.25	0.40
C	0.09	0.150
E	1.60	1.80
HE	2.30	2.70
Lp	0.20	0.40
θ	0°	5°